

# ULTRA FAST RECOVERY POWER RECTIFIER

## 1N5811D3

Variant Options D3A to D3H

- DLCC3 - Light Weight Hermetic Ceramic Surface Mount Package is designed as a drop In replacement for "D-5B" / "E-MELF" package†
- Ultra Fast Reverse Recovery
- Switching Power Supply Applications
- Space Level and High-Reliability Screening Options Available



## ABSOLUTE MAXIMUM RATINGS (T<sub>A</sub> = 25°C unless otherwise stated)

V <sub>BR</sub>	Breakdown Voltage	160V
V <sub>RRM</sub>	Working Peak Reverse Voltage	150V
I <sub>O</sub>	Maximum Rectified Current I <sub>O1</sub> = T <sub>A</sub> +55°C <sup>(1)</sup> Derate above T <sub>A</sub> 55°C	3.0A 25mA/°C
I <sub>FSM</sub>	Surge Current, t <sub>p</sub> = 8.3ms <sup>(2)</sup>	125A
T <sub>J</sub>	Junction Temperature Range	-65 to +175°C
T <sub>stg</sub>	Storage Temperature Range	-65 to +175°C

## THERMAL PROPERTIES

Symbols	Parameters	Max.	Units
R <sub>θJS(PIN)</sub>	Thermal Resistance, Junction To Solder Pads T <sub>SP</sub> = 25°C	17	°C/W
R <sub>θJA(PCB)<sup>(3)</sup></sub>	Thermal Resistance, Junction To Ambient, On PCB	50	°C/W
R <sub>θJA(PCB)<sup>(4)</sup></sub>	Thermal Resistance, Junction To Ambient, On PCB	117	°C/W

### Notes

- (1) I<sub>O1</sub> is rated at 3.0A @ T<sub>A</sub> = 55°C for PC boards where thermal resistance from mounting point to ambient is sufficiently controlled where T<sub>J(Max)</sub> does not exceed 175°C; This equates to R<sub>θJA(PCB)</sub> ≤ 52°C/W.
- (2) T<sub>A</sub> = 25°C @ I<sub>O</sub>=3.0A and V<sub>RRM</sub> for ten 8.3ms surges at 1 minute intervals.
- (3) PCB = FR4, 0.0625 Inch (1.59mm) thick, single layer, 1.0-Oz Cu, Pad Size, (1.0" x 1.0"), (645mm x 645mm) , horizontal in still air.
- (4) PCB = FR4, 0.0625 Inch (1.59mm) thick, single layer, 1.0-Oz Cu, Pad Size, (0.070" x 0.155")‡, (1.78mm x 3.94mm) ‡, horizontal in still air. I<sub>O1</sub> is rated at 1.5A @ T<sub>A</sub> = 55°C for PC boards where R<sub>θJA(PCB)</sub> ≤ 120°C/W. Derate at 12.5mA/°C above T<sub>A</sub> = 55°C in this case.

‡ Recommended solder pad layout dimensions for this device, as detailed within this datasheet for the D-5B device.

Semelab Ltd reserves the right to change test conditions, parameter limits and package dimensions without notice. Information furnished by Semelab is believed to be both accurate and reliable at the time of going to press. However Semelab assumes no responsibility for any errors or omissions discovered in its use. Semelab encourages customers to verify that datasheets are current before placing an order.



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### ELECTRICAL CHARACTERISTICS ( $T_A = 25^\circ\text{C}$ unless otherwise stated)

Symbols	Parameters	Test Conditions	Min.	Typ.	Max.	Units
$V_{BR}^{(5)}$	Breakdown Voltage	$I_R = 100\mu\text{A}$	160			
		$T_A = -65^\circ\text{C}$	150			
$V_F^{(5)}$	Forward Voltage	$I_F = 3.0\text{A}$			0.865	V
		$I_F = 4.0\text{A}$			0.875	
		$T_A = 125^\circ\text{C}$			0.800	
		$T_A = -65^\circ\text{C}$			1.075	
		$I_F = 6.0\text{A}$			0.925	
$I_R^{(5)}$	Reverse Current	$V_R = 150\text{V}$			5.0	$\mu\text{A}$
		$T_A = 125^\circ\text{C}$			525	

### DYNAMIC CHARACTERISTICS

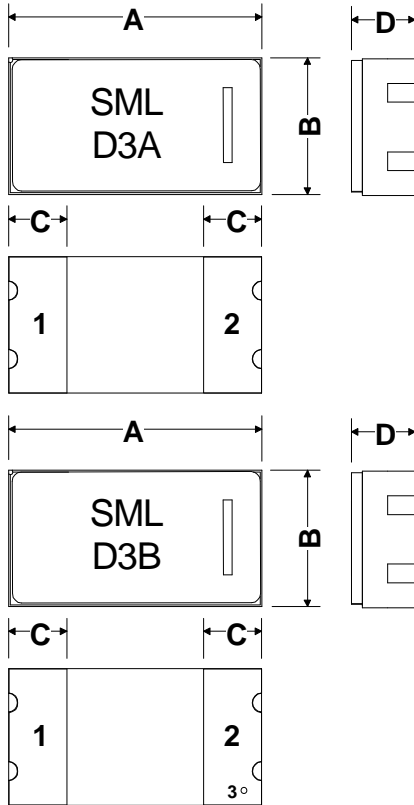
$t_{rr}$	Reverse Recovery Time	$I_F = I_{RM} = 1.0\text{A}$ $I_{REC} = 0.1\text{A}$ $di/dt = 100\text{A}/\mu\text{s}$ (min)		50		ns
$V_{fr}$	Forward Recovery Voltage	$I_F = 500\text{mA}$ $T_r = 8\text{ns}$		2.2		V
$t_{fr}$	Forward Recovery Time	$I_F = 500\text{mA}$ , $T_p \geq 20\text{ns}$ , $T_r = 8\text{ns}$		15		ns
$C_J$	Capacitance	$V_R = 10\text{V}$ $f = 1.0\text{MHz}$		85		pF

#### Notes

(5) Pulse Width  $\leq 300\mu\text{s}$ ,  $\delta \leq 2\%$

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## MECHANICAL DATA



### DLCC3 Variants A, C, D, E

Variant	
D3A	Au Plated Terminals
D3C	Tape & Reel Option
D3D	Hot Solder Dipped Terminals
D3E	Hot Solder Dipped Terminals & Tape & Reel Option

Pin Out	
PAD 1	ANODE
PAD 2	CATHODE

DIMENSION	mm	Inches
A	7.00 ±0.10	0.275 ±0.004
B	3.75 ±0.10	0.143 ±0.004
C	1.60 ±0.10	0.063 ±0.004
D	1.76 ±0.10	0.069 ±0.004

### DLCC3 Variants B, F, G, H

Variant	
D3B	Au Plated Terminals
D3F	Tape & Reel Option
D3G	Hot Solder Dipped Terminals
D3H	Hot Solder Dipped Terminals & Tape & Reel Option

Pin Out	
PAD 1	ANODE
PAD 2	CATHODE
PAD 3	LID CONTACT TO CATHODE*

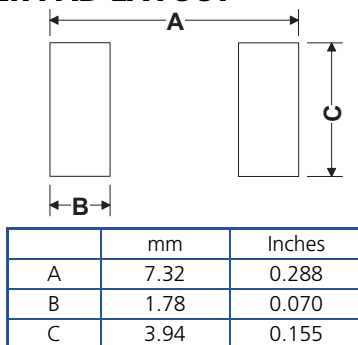
  

DIMENSION	mm	Inches
A	7.00 ±0.10	0.275 ±0.004
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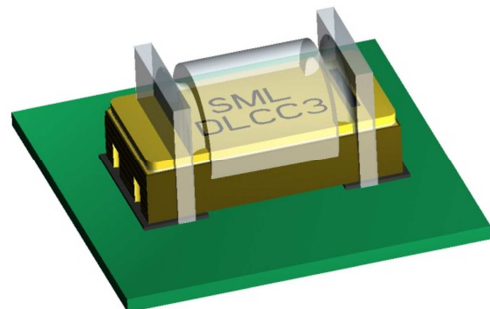
\* The additional contact provides a connection to the lid in the application. Connecting the metal lid to a known electrical potential stops deep dielectric discharge in space applications; see the Space Weather link [www.semelab.co.uk/dlcc3.html](http://www.semelab.co.uk/dlcc3.html) on the Semelab web site. The Package variant & options are to be specified when placing the order.

† The DLCC3 package design takes full advantage of the proven high reliability pedigree of the HTCC surface mount packaging technology, which is easily integrated for automated assembly. Semelab has taken the existing standards for ceramic surface mount package manufacture and added additional design features to enhance thermal performance, to present a competitive alternative for high reliability applications.

## SOLDER PAD LAYOUT



Soldering temperature should be 260°C for a maximum of 10 seconds.



The physical dimensions for the DLCC3 ceramic package are designed to be different from the published dimensions for the "D-5B" and "E-MELF" outlines. The DLCC3 design fully utilises the recommended solder footprint for the "D-5B" / "E-MELF" Package, and as such presents a drop in replacement for existing board designs.

## PACKAGE MASS

Gold Plated Solder Pad Finish = 150mg

# ULTRA FAST RECOVERY POWER RECTIFIER 1N5811D3



## SCREENING OPTIONS

Space Level (JQRS/ESA) and High Reliability options are available in accordance with the [High Reliability and Screening Options Handbook](#) available for download from the from the TT electronics Semelab web site.

ESA Quality Level Products are based on the testing procedures specified in the generic ESCC 5000 and in the corresponding part detail specifications.

Semelab's QR216 and QR217 processing specifications (JQRS), in conjunction with the companies ISO 9001:2000 approval present a viable alternative to the American MIL-PRF-19500 space level processing.

QR217 (Space Level Quality Conformance) is based on the quality conformance inspection requirements of MIL-PRF-19500 groups A (table V), B (table VIa), C (table VII) and also ESA / ESCC 5000 (chart F4) lot validation tests.

QR216 (Space Level Screening) is based on the screening requirements of MIL-PRF-19500 (table IV) and also ESA /ESCC 5000 (chart F3).

JQRS parts are processed to the device data sheet and screened to QR216 with conformance testing to Q217 groups A and B in accordance with MIL-STD-750 methods and procedures.

Additional conformance options are available, for example Pre-Cap Visual Inspection, Buy-Off Visit or Data Packs. These are chargeable and must be specified at the order stage (See Ordering Information). Minimum order quantities may apply.

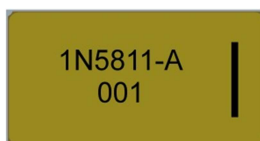
Alternative or additional customer specific conformance or screening requirements would be considered. Contact Semelab sales with enquiries.

## MARKING DETAILS

Parts can be laser marked with approximately 7 characters on two lines and always includes cathode identification. Typical marking would include part or specification number, week of seal or serial number subject to available space and legibility.

Customer specific marking requirements can be arranged at the time of order.

Example Marking:



## ORDERING INFORMATION

Part numbers are built up from Type, Package Variant, and screening level. The part numbers are extended to include the additional options as shown below.

Type – See Main Part Number & Variant Options

Package Variant – See Mechanical Data

Screening Level – See Screening Options (ESA / JQRS)

Additional Options:

Customer Pre-Cap Visual Inspection	.CVP
Customer Buy-Off visit	.CVB
Data Pack	.DA
Solderability Samples	.SS
Scanning Electron Microscopy	.SEM
Radiography (X-ray)	.XRAY
Total Dose Radiation Test	.RAD
MIL-PRF-19500 (QR217)	
Group B charge	.GRPB
Group B destructive mechanical samples	.GBDM (12 pieces)
Group C charge	.GRPC
Group C destructive electrical samples	.GCDE (12 pieces)
Group C destructive mechanical samples	.GCDM (6 pieces)
ESA/ESCC	
Lot Validation Testing (subgroup 1) charge	.LVT1
LVT1 destructive samples (environmental)	.L1DE (15 pieces)
LVT1 destructive samples (mechanical)	.L1DM (15 pieces)
Lot Validation Testing (subgroup 2) charge	.LVT2
LVT2 endurance samples (electrical)	.L2D (15 pieces)
Lot Validation Testing (subgroup 3) charge	.LVT3
LVT3 destructive samples (mechanical)	.L3D (5 pieces)

Additional Option Notes:

- 1) All 'Additional Options' are chargeable and must be specified at order stage.
- 2) When Group B,C or LVT is required, additional electrical and mechanical destructive samples must be ordered
- 3) All destructive samples are marked the same as other production parts unless otherwise requested.

Example ordering information:

The following example is for the 1N5811D3 part with package variant B, JQRS screening, additional Group C conformance testing and a Data pack.

Part Numbers:

- 1N5811D3B-JQRS (Include quantity for flight parts)
- 1N5811D3B-JQRS.GRPC (chargeable conformance option)
- 1N5811D3B-JQRS.GCDE (charge for destructive parts)
- 1N5811D3B-JQRS.GCDM (charge for destructive parts)
- 1N5811D3B-JQRS.DA (charge for Data pack)

Customers with any specific requirements (e.g. marking or screening) may be supplied with a similar alternative part number (there is maximum 20 character limit to part numbers). Contact Semelab sales with enquiries.

High Reliability and Screening Options Handbook link: [http://www.semelab.co.uk/pdf/misc/documents/hirel\\_and\\_screening\\_options.pdf](http://www.semelab.co.uk/pdf/misc/documents/hirel_and_screening_options.pdf)